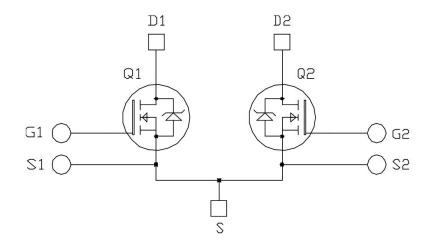
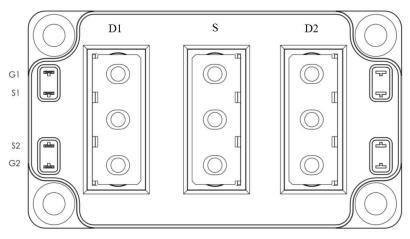
# MSCSM170DUM039AG

### **Dual Common Source SiC MOSFET Power Module**

### **Product Overview**

The MSCSM170DUM039AG device is a 1700V/523A dual common source silicon carbide (SiC) MOSFET power module.





**Note:** All ratings at  $T_J = 25$  °C, unless otherwise specified.

**⚠** CAUTION

These devices are sensitive to electrostatic discharge. Proper handling procedures must be followed.

#### **Features**

The following are the key features of MSCSM170DUM039AG device:

- SiC Power MOSFET
  - Low R<sub>DS(on)</sub>
  - High temperature performance
- Kelvin source for easy drive
- Low stray inductance
- High level of integration
- · Aluminum Nitride (AIN) substrate for improved thermal performance
- M5 power connectors

### **Benefits**

The following are the benefits of MSCSM170DUM039AG device:

- · Outstanding performance at high frequency operation
- Direct mounting to heatsink (isolated package)
- Low junction-to-case thermal resistance
- Low profile
- RoHS compliant

### **Application**

The following are the applications of MSCSM170DUM039AG device:

- AC switches
- Switched mode power supplies
- Uninterruptible power supplies

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#### 1. **Electrical Specifications**

This section provides the electrical specifications of the MSCSM170DUM039AG device.

#### 1.1 **SiC MOSFET Characteristics (Per SiC MOSFET)**

The following table lists the absolute maximum ratings of MSCSM170DUM039AG device.

**Table 1-1. Absolute Maximum Ratings** 

Symbol	Parameter	Parameter		Unit
V <sub>DSS</sub>	Drain-Source voltage	Drain-Source voltage		V
I <sub>D</sub>	Continuous drain current	T <sub>C</sub> = 25 °C	523	Α
		T <sub>C</sub> = 80 °C	416	
I <sub>DM</sub>	Pulsed drain current	Pulsed drain current		
V <sub>GSmax</sub>	Gate-Source voltage	Gate-Source voltage		V
R <sub>DS(on)</sub>	Drain-Source ON resistance		5	mΩ
P <sub>D</sub>	Power dissipation	T <sub>C</sub> = 25 °C	2400	W

The following table lists the electrical characteristics of MSCSM170DUM039AG device.

**Table 1-2. Electrical Characteristics** 

Symbol	Characteristic	Test Conditions		Min.	Тур.	Max.	Unit
I <sub>DSS</sub>	Zero gate voltage drain current	$V_{GS} = 0V$ $V_{DS} = 1700V$		_	90	900	μΑ
R <sub>DS(on)</sub> Drain–Source on resistance			T <sub>J</sub> = 25 °C	_	3.9	5	mΩ
			T <sub>J</sub> = 175 °C	_	6.8	_	
V <sub>GS(th)</sub>	Gate threshold voltage	$V_{GS} = V_{DS}$ $I_D = 22.5 \text{ mA}$		1.8	3.3	_	V
I <sub>GSS</sub>	Gate–Source leakage current	V <sub>GS</sub> = 20V V <sub>DS</sub> = 0V		_	_	900	nA

The following table lists the dynamic characteristics of MSCSM170DUM039AG device.

**Table 1-3. Dynamic Characteristics** 

Symbol	Characteristic	Test Conditions		Min.	Тур.	Max.	Unit
C <sub>iss</sub>	Input capacitance	V <sub>GS</sub> = 0V V <sub>DS</sub> = 1000V f = 1 MHz		_	29.7	_	nF
Coss	Output capacitance			_	1.3	_	
C <sub>rss</sub>	Reverse transfer capacitance			_	0.09	_	
Qg	Total gate charge	$V_{GS} = -5V/20V$ $V_{Bus} = 850V$ $I_{D} = 270A$		_	1602	_	nC
Qgs	Gate-Source charge			_	441	_	
Qgd	Gate-Drain charge			_	243	_	
T <sub>d(on)</sub>	Turn-on delay time	V <sub>GS</sub> = -5V/20V	T <sub>J</sub> = 150 °C	_	75	_	ns
Tr	Rise time	V <sub>Bus</sub> = 900V		_	75	_	
T <sub>d(off)</sub>	Turn-off delay time	I <sub>D</sub> = 450A		_	153	_	
Tf	Fall time	$R_{Gon}$ = 3.2Ω $R_{Goff}$ = 1.8Ω			56	_	
Eon	Turn-on energy	V <sub>GS</sub> = -5V/20V	T <sub>J</sub> = 150 °C	_	24.3	_	mJ
E <sub>off</sub>	Turn-off energy	$V_{Bus} = 900V$ $I_{D} = 450A$ $R_{Gon} = 3.2\Omega$ $R_{Goff} = 1.8\Omega$	TJ = 150 °C	_	10.8	_	
RGint	Internal gate resistance			_	0.65	_	Ω
RthJC	Junction-to-case thermal resistance			_	_	0.063	°C/W

The following table lists the body diode ratings and characteristics of MSCSM170DUM039AG device.

**Table 1-4. Body Diode Ratings and Characteristics** 

Symbol	Characteristic	Test Conditions	Min.	Тур.	Max.	Unit
V <sub>SD</sub>	Diode forward voltage	$V_{GS} = 0V$ $I_{SD} = 270A$	_	3.7	_	V
		$V_{GS} = -5V$ $I_{SD} = 270A$	_	3.9	_	
t <sub>rr</sub>	Reverse recovery time	I <sub>SD</sub> = 270A	_	27	_	ns
Q <sub>rr</sub>	Reverse recovery charge	$V_{GS} = -5V$	_	5.9	_	μC
Irr	Reverse recovery current	$V_R = 900V$ $di_F/dt = 9000A/\mu s$	_	414	_	A

### 1.2 Thermal and Package Characteristics

The following table lists the thermal and package characteristics of the MSCSM170DUM039AG device.

**Table 1-5. Thermal and Package Characteristics** 

Symbol	Characteristic			Min.	Max.	Unit
V <sub>ISOL</sub>	RMS isolation voltage, any terminal	RMS isolation voltage, any terminal to case t = 1 min, 50 Hz/60 Hz			_	V
TJ	Operating junction temperature range	Operating junction temperature range			175	°C
T <sub>JOP</sub>	Recommended junction temperature	Recommended junction temperature under switching conditions			T <sub>Jmax</sub> –25	
T <sub>STG</sub>	Storage case temperature			-40	125	
T <sub>C</sub>	Operating case temperature	Operating case temperature			125	
Torque	Mounting torque To heatsink M6			3	5	N.m
		For terminals	M5	2	3.5	
Wt	Package weight			_	320	g

### 1.3 Typical SiC MOSFET Performance Curve (Per SiC MOSFET)

This section shows the typical SiC MOSFET performance curves of the MSCSM170DUM039AG device.

Figure 1-1. Junction-to-Heatsink Thermal Impedance

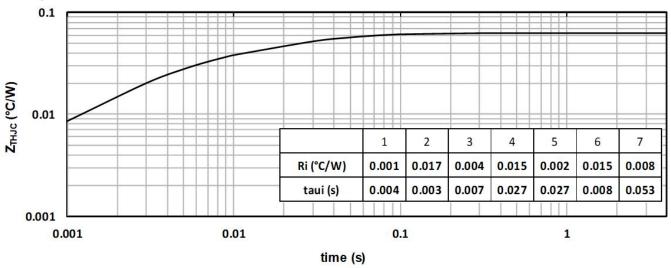


Figure 1-2. Output Characteristics,  $T_J = 25$  °C

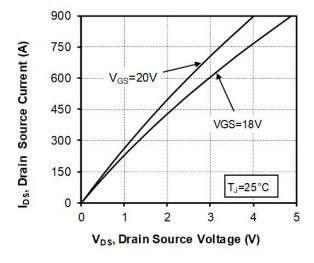


Figure 1-3. Output Characteristics, T<sub>J</sub> = 175 °C

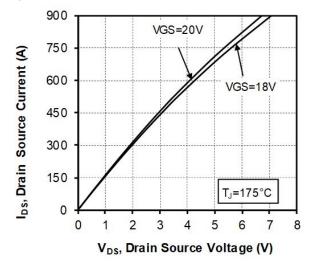


Figure 1-4. Normalized R<sub>DS(on)</sub> vs. Temperature

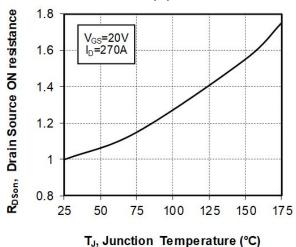


Figure 1-5. Transfer Characteristics

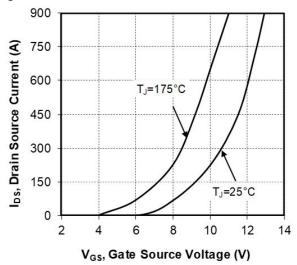


Figure 1-6. Switching Energy vs. Rg

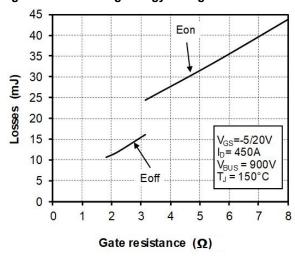


Figure 1-7. Switching Energy vs. Current

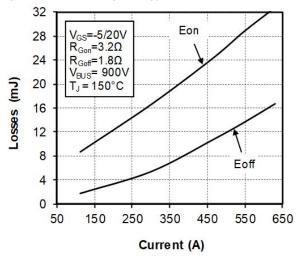


Figure 1-8. Capacitance vs. Drain Source Voltage

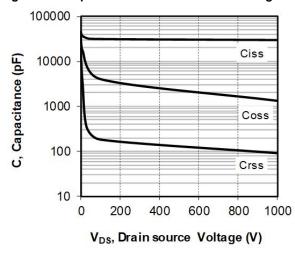
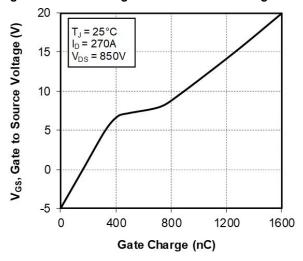
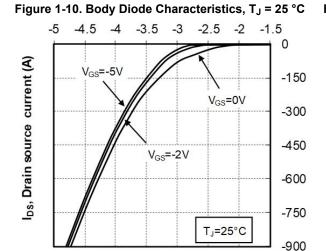


Figure 1-9. Gate Charge vs. Gate Source Voltage

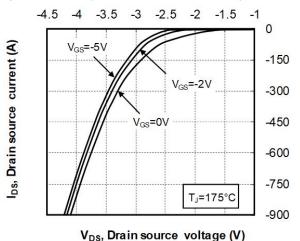




V<sub>DS</sub>, Drain source voltage (V)

Figure 1-11. 3<sup>rd</sup> Quadrant Characteristics, T<sub>J</sub> = 25 °C -5 -3 -2 0 T<sub>J</sub>=25°C Ds, Drain source current (A) -150 V<sub>GS</sub>=0V -300 -450 -600 -750 V<sub>GS</sub>=20V VGS=18V -900 V<sub>DS</sub>, Drain source voltage (V)

Figure 1-12. Body Diode Characteristics, T<sub>J</sub> = 175 °C Figure 1-13. 3<sup>rd</sup> Quadrant Characteristics, T<sub>J</sub> = 175 °C



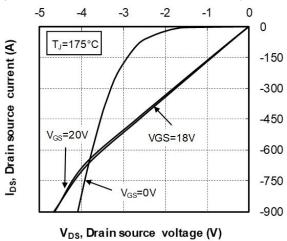
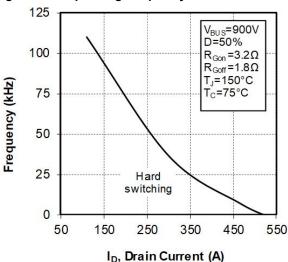


Figure 1-14. Operating Frequency vs. Drain Current



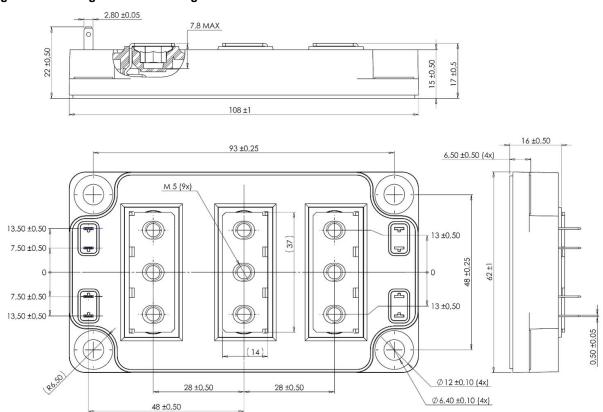
### 2. Package Specifications

The following section shows the package specification of the MSCSM170DUM039AG device.

### 2.1 Package Outline

The following figure shows the package outline drawing of the MSCSM170DUM039AG device. The dimensions in the following figure are in millimeters.

Figure 2-1. Package Outline Drawing



### MSCSM170DUM039AG

**Revision History** 

## 3. Revision History

Revision	Date	Description
Α	12/2021	Initial Revision

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